













VIP Geometry



VIP detector module is made of pixelated CdTe detectors with trapezoidal shape. It is bonded to the thinned ROC and then Module block consists of VIP detector modules and contains 450 voxels/cm³. The voxel size is 1mm x 1mm x 2mm.

VIP sector is made of 4 module blocks connected to the same electronic bus.



VIP Distinctive Features



When 66 of the VIP sectors are put together, they form a cylindrical seamless PET scanner. A total number of the detector voxels is 6,336,000. Thus, the VIP has 6,336,000 independent readout electronic channels. ✤ Greatly improve the spatial resolution due to true 3D impact information (negligible parallax error).

 Has excellent energy resolution . FWHM ~1.57% at 511 keV @ room temperature.
 Eliminating most of the scattered events and thus achieve high signal-to-noise ratio

Has adequate detection efficiency for 511 keV photons thanks to the high CdTe stopping power and seamless geometry.



Performance Evaluation

NEMA NU 4-2008 small phantom



Mokhtar Chmeissani, Symposium "Advanced Semiconductor Detectors for Medical Applications" 13-02-2015



Performance Evaluation





Performance Evaluation

Characteri stic	VIP NEMA NU 4- 2008	NEMA NU 4- 2008: One of the best results	VIP NEMIA NU 2- 2001	NEMA NU 2-2001: One of the best results
Scatter fraction	0.73%	7.8% (Inveon DPET)	3.95%	34% (PENN-PET)
Sensitivity	21 cps/kBq	16.98 cps/kBq (ClearPET)	14.37 cps/kBq	6.6 cps/kBq (HR+)
Radial spatial resolution near the center of FOV	0.75 mm	1.5 mm (rPET-1)	0.694 mm	2.3 mm (CdTe based PET) 4.1 mm (G-PET)







VIP Compton Camera







Compton Camera Principle



 In a Compton camera the gamma photons emitted suffer a Compton interaction in the lrst detector (scatterer) and a photoelectric
 absorption in the 2nd (Absorber).

$$\cos \vartheta = 1 - mc^2 \left(\frac{1}{E_{total} - E_{scatter}} - \frac{1}{E_{total}} \right)$$

• Electronic collimation exploits the Compton interaction to reconstruct a cone surface in which the emitting source lay.



The intersection of cone surfaces allows to determine the source position.



VIP-CC Sensitivity



VIP Compton camera sensitivity for different activities of ¹⁸F isotope. The good energy resolution of the CdTe detector allow us to discard most of the random and scattered events achieving a signal-to-noise ratio of 93%.







VIP-CC Derenzo Phantom



FIGURE 6.28: *Top:* scheme of the phantom. *Bottom:* reconstructed image with LM-OSEM and corresponding line profile of the 1.5 mm diameter rods. [75]







VIP-PEM Design



Figure 1. Basic unit detector and detector specifics.

• VIP mammography consists of two parallel paddles, each one hosting one sliding detector head. Each head has 64000 voxel/channels.

• The head section is 170 mm wide along the x-axis and 40 mm wide along the z-axis, and the two detector heads must slide axially for a complete scan of the 170 mm x 60 mm x 240 mm FOV.



Naviscan PEM design



FIGURE 1. (A) PEM Flex Solo II system. (B) Close-up of detectors. (C) Illustration of in-planes and cross-planes. Four cardinal positions (i, ii, iii, and iv) within PEM Flex FOV used to investigate quantification consistency.



VIP Versus Naviscan Phantom Image Quality









VIP Design Architect





Architecture of the pixel readout electronics.

Architecture of the readout integrated circuit for the pixelated CdTe detectors of the VIP project.



Detector/Pixel Specifications

Specification

Detector size Voxel size Detector DC bias voltage Detector leakage current Electron/Hole drift time **Pixel capacitance** Coincidence time window Energy resolution Energy resolution Maximum Jitter of time stamp Maximum power consumption Value

10x10x2 mm³ 1x1x2 mm³ 1000 V/2mm 1000 pA/pixel 35 ns/385 ns 80 fF 20 nsec

10bits for 511 keV 10 ns 200 µW/pixel



CdTe Energy Resolution





CdTe Time Resolution



to handle high FDG dose



VIP Wafer production



Single submission
12 Wafers produced
Delivered in May 2014
One wafer diced for basic tests
11 sent to IZM for UBM. We received them back in the 2nd week of July.
One wafer sent to DISCO-HiTech for dicing/thinning down to 50um

VIP wafer thinned to 50um, diced and put on tape.



VIP Wafer Map



Typical results after probing. Each wafer can provide enough chips of class A for 2 Modules (80 chips)



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FPGA PCB in our hands. Passed the test. 100 PCBs will be sent this week to be populated with SMD components.

Rigid-flex PCB (255um) in our hands. Passed the test. 100 PCBs were sent to be populated with SMD components.

Bridge PCB in our hand. It will be process Later





Original design was based on 3D plastic PCB but after long R&D we realized that it does not fit for 250um solder balls. We decided to go for 3D Ceramic PCB. The delivery will be by end of November









Solder Ball (250um) after deposition with Pactech machine

Solder Ball (250um) after reflow with formic acid using ATV oven





Bonding CdTe-to-VIP ASIC using FC150



Pick & Place and Wirebonding



VIP Ring Construction





VIP Ring Construction







Thank you for your attention